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In situ "Curing"
 Pressure Sensitive
 Electrically Insulating
 Film Adhesive

IDEAL FOR:

- Component Attach
- Heat Sink Attach
- Substrate Attach

DESCRIPTION:

CB7208-EDA2 is a modified version of TP7208 designed to have improved bond strength at elevated temperature. CB7208-EDA2 is an aluminum nitride filled, low bond strength thermoplastic film adhesive. It is designed for bonding heat sinks, component, and substrate. CB7208-EDA2 has good thermal conductivity. As applied, it provides >100 psi bond strength that will improve to over 600 psi in-situ over time.

AVAILABILITY:

CB7208-EDA2 is available in sheet sizes or as custom preforms. Standard thicknesses are 0.006" and 0.010". Special thicknesses are available.

APPLICATION PROCEDURES:

- (1) Cut to desired size.
- (2) Remove one side of releasel liner from adhesive.
- (3) Place on substrate or component with rolling finger pressure, then remove the other release liner.
- (4) Place component on substrate with insertion pressure of 10 psi or more. More bond strength will develop in-situ over time during operation.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details. The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

COOL-BOND
CB7208-EDA2

TYPICAL PROPERTIES*

Electrical Resistivity (25 °C/ As Placed)	>1x10¹⁴ ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	-25 ±10%
Lap-Shear Strength	<>200 psi <>1.4 N/mm²
Device Push-off Strength	>600 psi >4.1 N/mm²
Hardness (Type)	<40 (A)
Cured Density (gm/cc)	2.2 ±10%
Thermal Conductivity	25 Btu-in/hr-ft²-°F ±10% 3.6 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	110 ±15%
Maximum Continuous Operation Temp. (°C)	<150

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Temp/Bond Force

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
	Bond Force	
25°C	650 psi	
50°C	550 psi	
75°C	380 psi	
100°C	300 psi	
125°C	250 psi	

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
0-5°C	1 yr in sealed package